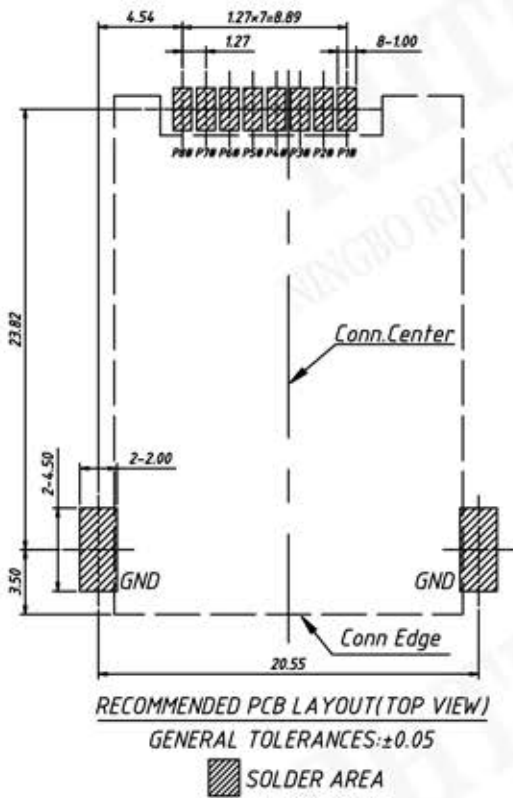
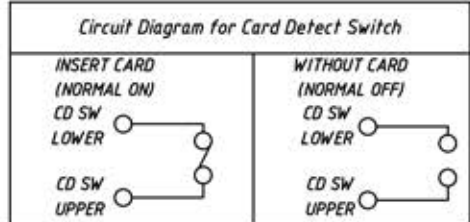


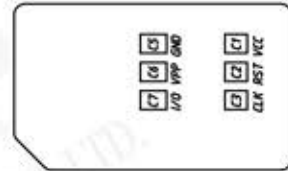
Pin No.	Description
P1 #	C1:VCC
P2 #	C5:GND
P3 #	C2:RST
P4 #	C6:VPP
P5 #	C3:CLK
P6 #	C7:I/O
P7 #	CD SW LOWER
P8 #	CD SW UPPER



Material:
Housing: Hi-Temp Plastic, UL 94 V-0 Rated.
Contact: Copper Alloy.
Shell: Stainless Steel, SUS 301, T=0.20mm.

Plating:
Contact area: G/F Plated over 30u" Nickel
Solder area: 80u" Tin Plated over 30u" Nickel.
Under plate: 30u" Min Nickel.
Shell: 30u" Min, Nickel Plated Over All, Solder Area: Gold Flash.

Electrical:
Current Rating: 0.5 A
Dielectric Withstanding Voltage: 250V AC/DC.
Insulation Resistance: 500MΩ Min.
Contact Resistance: 100mΩ Max.
Mating Cycles: 5000 Insertions.
Operating Temperature: -40°C TO +85°C



SIM Diagram
Chip face down

UNITS:mm	SHEET SIZE:A4		SCALE: ---
> 0~3	> 3~18	> 18~50	> 50~120
± 0.12	± 0.15	± 0.3	± 0.5